

# SOT1547-2

LFBGA257, plastic, low profile fine-pitch ball grid array package; 257 balls; 0.8 mm pitch; 14 mm x 14 mm x 1.45 mm body

30 July 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA257
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-275A -JJAC-1
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	18-07-2019
<b>Manufacturer package code</b>	98ASA01430D

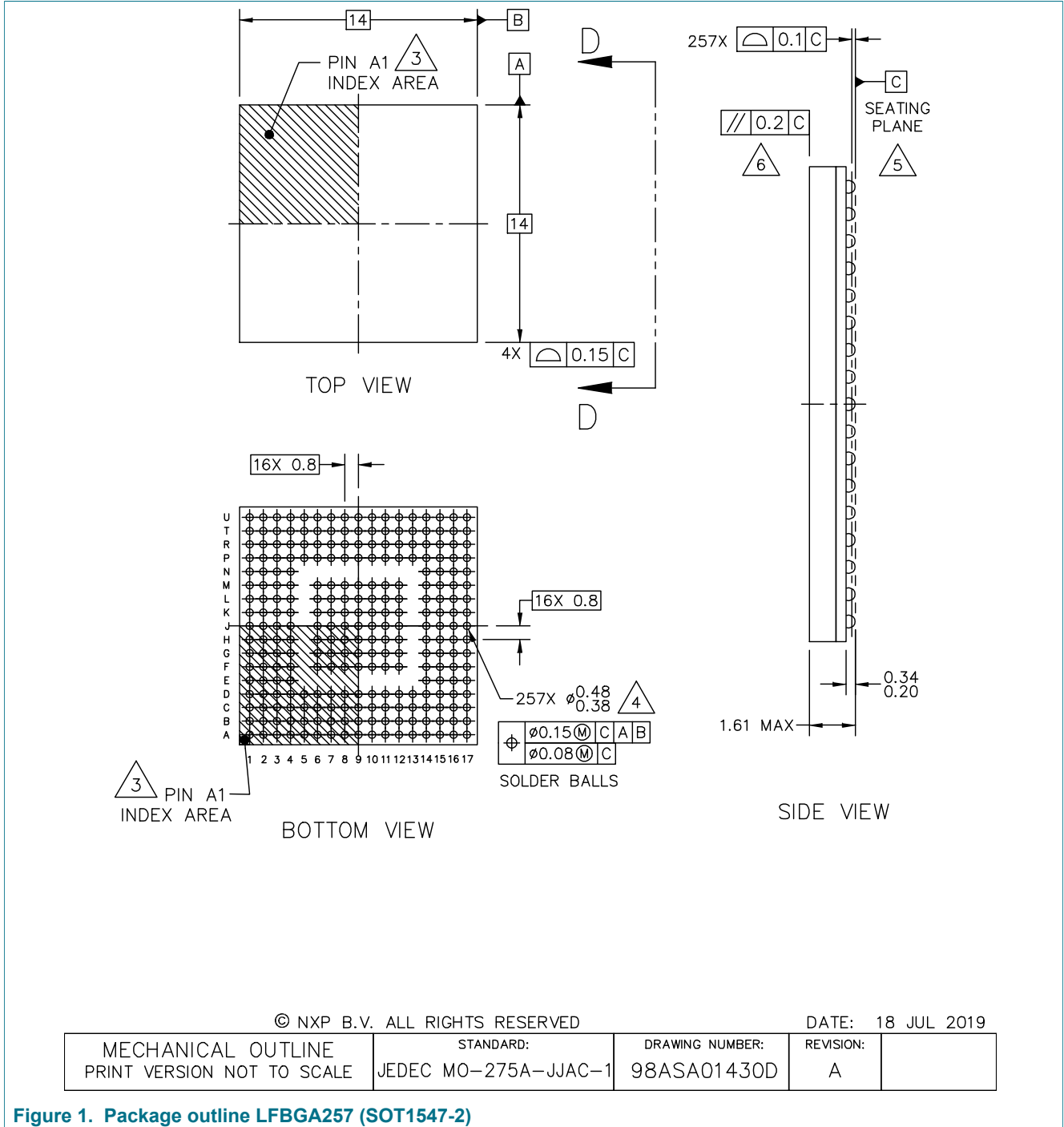
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	14	-	mm
package width	-	14	-	mm
package height	-	1.45	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	257	-	



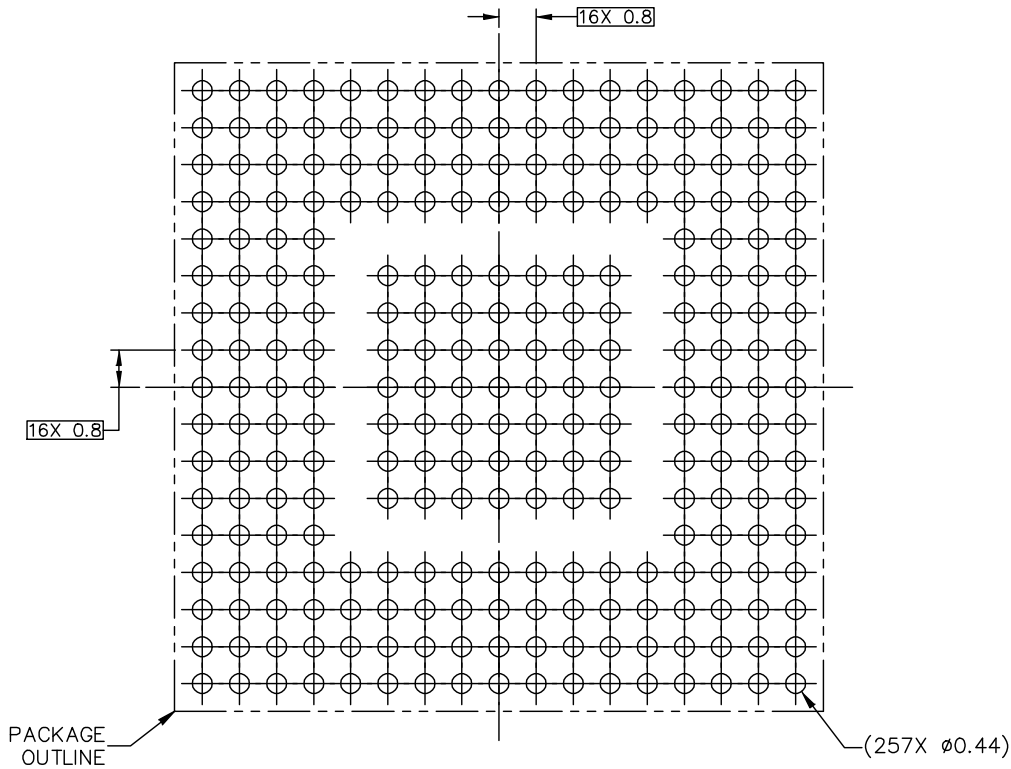
LFBGA257, plastic, low profile fine-pitch ball grid array package; 257 balls; 0.8 mm pitch; 14 mm x 14 mm x 1.45 mm body

2 Package outline



LFBGA257, plastic, low profile fine-pitch ball grid array package; 257 balls; 0.8 mm pitch; 14 mm x 14 mm x 1.45 mm body

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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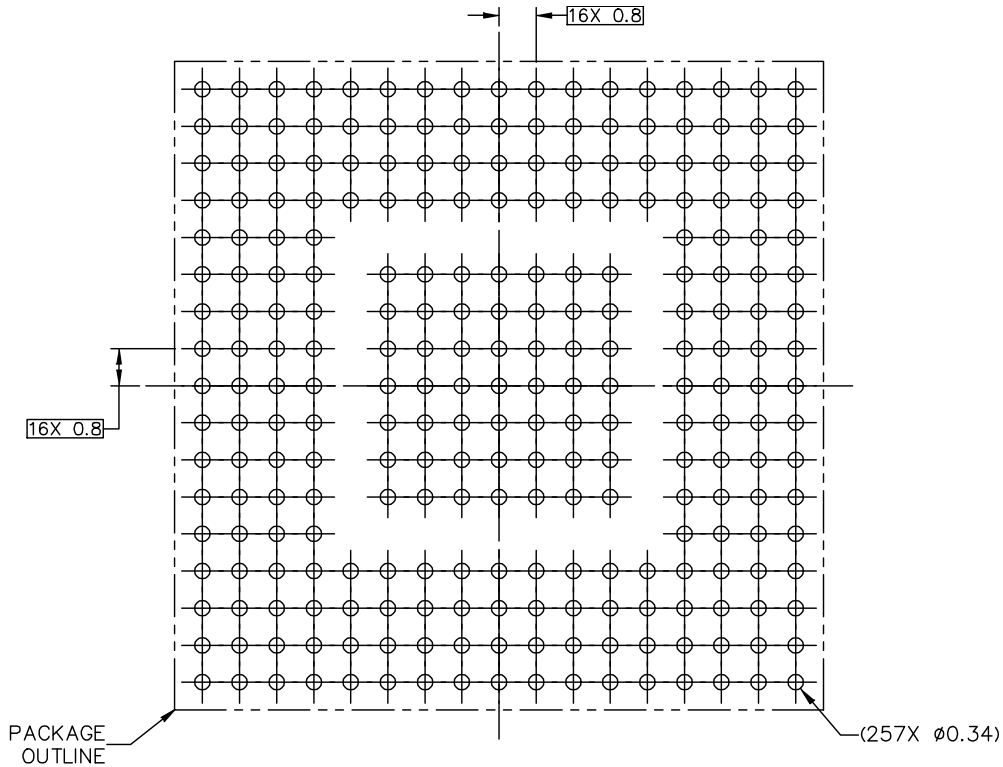
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DATE: 18 JUL 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: JEDEC MO-275A-JJAC-1	DRAWING NUMBER: 98ASA01430D	REVISION: A	
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Figure 2. Reflow soldering footprint part1 of LFBGA257 (SOT1547-2)

LFBGA257, plastic, low profile fine-pitch ball grid array package; 257 balls; 0.8 mm pitch; 14 mm x 14 mm x 1.45 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

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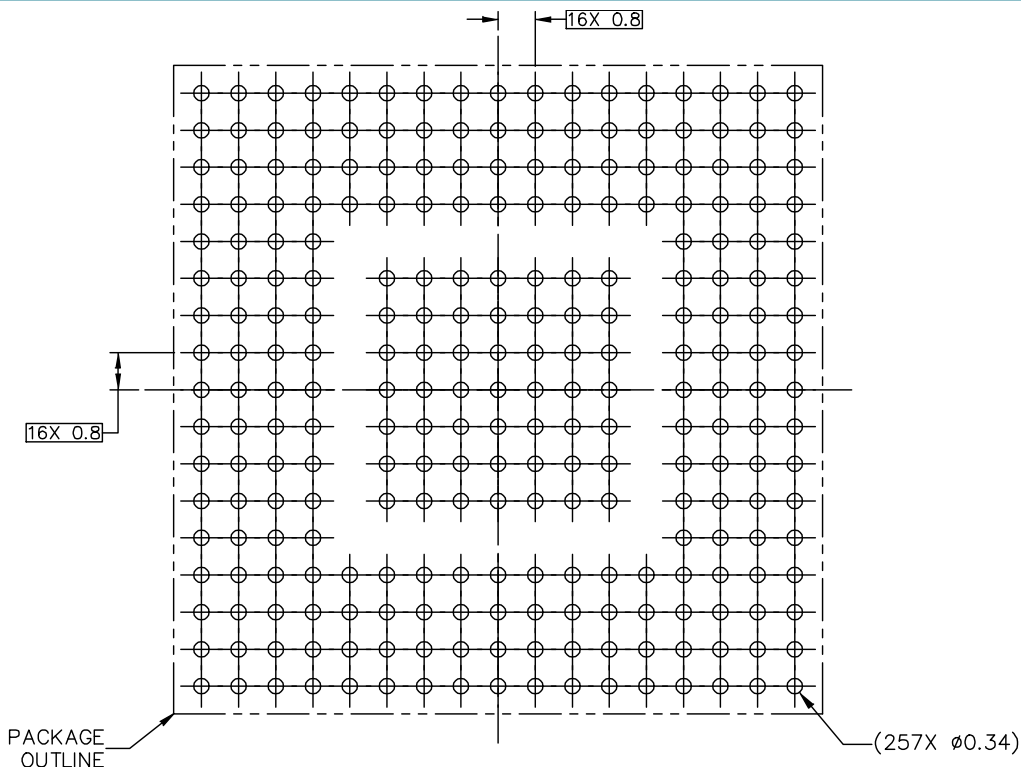
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Figure 3. Reflow soldering footprint part2 of LFBGA257 (SOT1547-2)

LFBGA257, plastic, low profile fine-pitch ball grid array package; 257 balls; 0.8 mm pitch; 14 mm x 14 mm x 1.45 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 of LFBGA257 (SOT1547-2)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note LFBGA257 (SOT1547-2)

## 4 Legal information

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